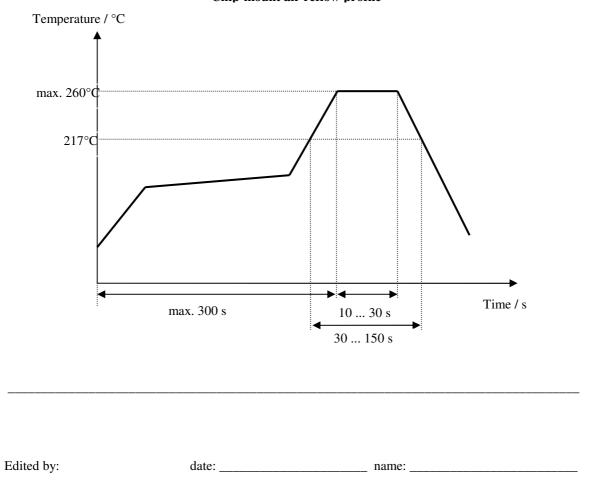


## 6. Air reflow temperature conditions

| conditions  | Exposure                    |
|---|-----------------------------|
| average ramp-up rate ( 30°C to 217°C )                  | less than 3°C/second        |
| > 100°C   | between 300 and 600 seconds |
| > 150°C   | between 240 and 500 seconds |
| >217°C  | between 30 and 150 seconds  |
| peak temperature  | max. 260°C                  |
| time within 5°C of peak temperature                     | between 10 and 30 seconds   |
| cool-down rate ( starting at peak temperature to 50°C ) | less than 6°C / second      |
| time from 30°C to peak temperature                      | no more than 300 seconds    |



Chip-mount air reflow profile